



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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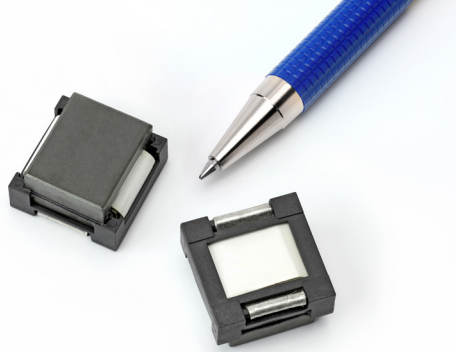
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HC2LP

Low profile, high current power inductors



Product description

- Compact footprint
- Designed for high density, high current/low voltage applications
- Foil technology that adds higher reliability factor over the traditional magnet wire used for higher frequency circuit designs
- Frequency Range up to 1MHz
- Ferrite core material

Applications

- Distributed power systems DC-DC converters
- General-purpose low voltage supplies
- Computer systems
- Servers
- Point of Load (POL) converters
- Industrial Equipment
- Networking/Telecom power supplies

Environmental data

- Storage temperature range (component): -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise).
- Solder reflow temperature: J-STD-020D compliant.

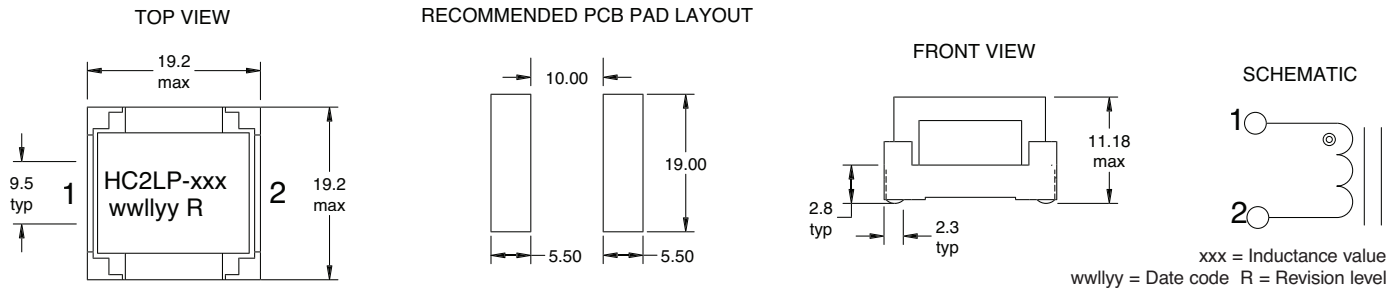


Product specifications

Part number	OCL ¹ (μH) ±20%	I _{rms} ² amps (approx.)	I _{sat} ³ amps (approx.)	DCR ⁴ (Ω) maximum @ 20°C	Volt-μsec ⁵ (V-μs)
HC2LP-R47-R	.52	52.9	63.75	.0006	6.87
HC2LP-R68-R	.63	52.9	50.00	.0006	6.87
HC2LP-1R0-R	1.15	33.0	42.50	.0013	10.31
HC2LP-2R2-R	2.00	24.3	31.90	.0023	13.75
HC2LP-4R7-R	4.55	17.0	21.25	.0046	20.62
HC2LP-6R0-R	6.00	17.0	16.50	.0046	20.62

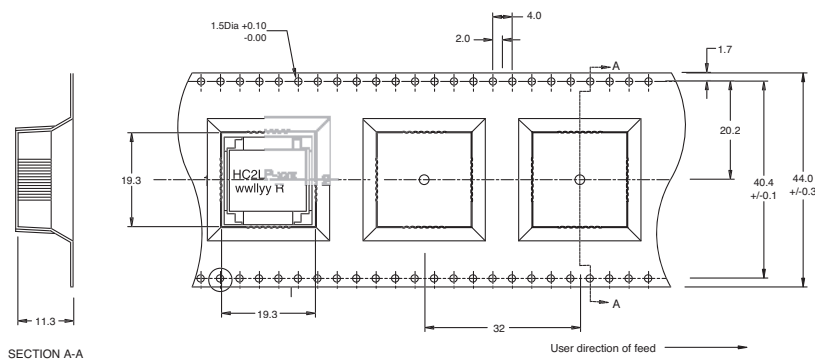
- Open Circuit Inductance Test Parameters: 300kHz, 0.250 Vrms, 0.0 Adc
- DC current for an approximate temperature change of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- Peak current for approximately 30% rolloff.
- Values @ 20°C
- Applied Volt-Time product (V-μs) across the inductor. This value represents the applied V-μs at 300kHz necessary to generate a core loss equal to 10% of the total losses for 40°C temperature rise.

Dimensions—mm

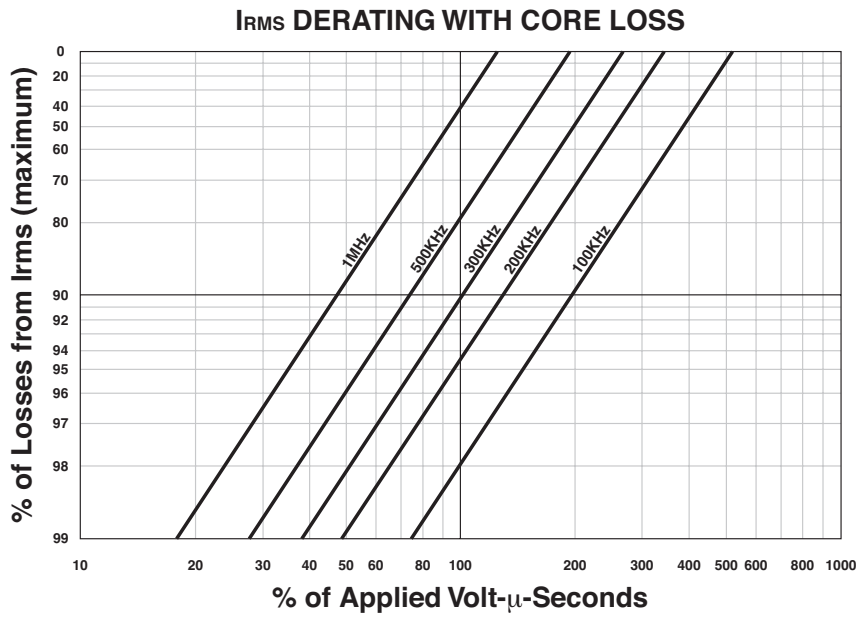


Packaging information (mm)

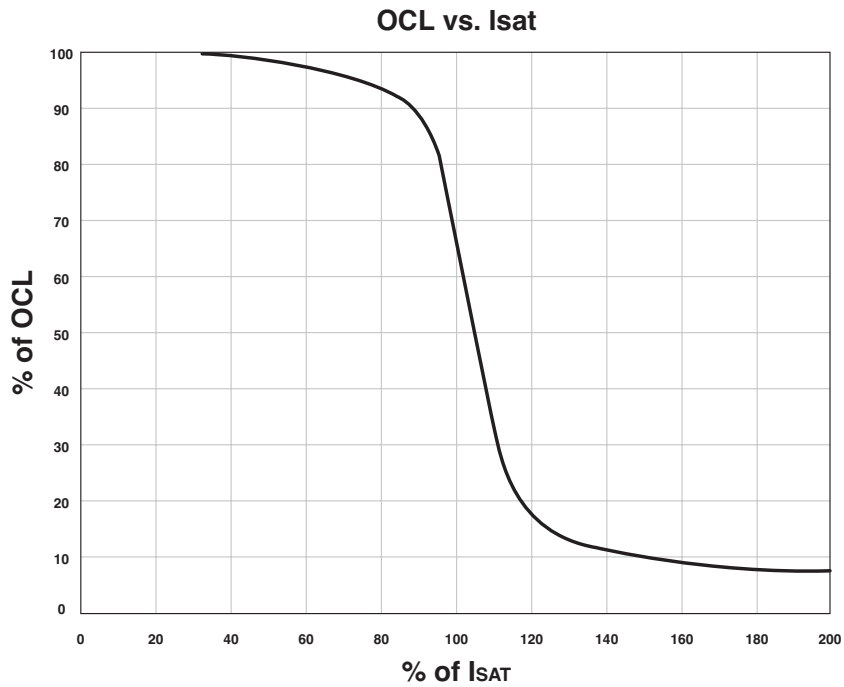
Supplied in tape and reel packaging, 130 parts per 13" reel.



Core loss



Inductance Characteristics



Solder reflow profile

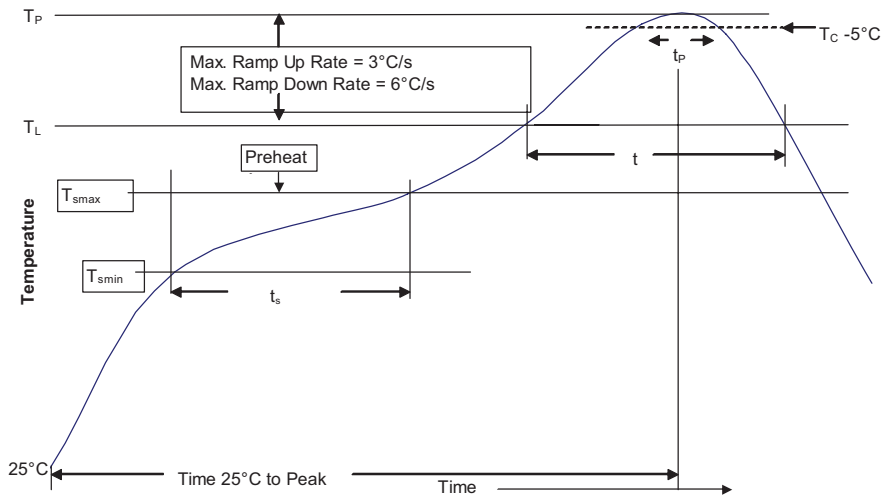


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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